Hiner-pack® SVFWS Carrier 200 mm

Compatible with industry-standard film frames for wafer processing and inspection

For secure and contamination-free semiconductor wafer transport, vacuum-formed flex frame single wafer shippers offer superior design and material performance. The clamshell enclosure isolates the wafer surface while protecting the flex, dicing, or film frame from mechanical impact. Fabricated from conductive PET, these ESD-safe wafer carriers neutralize static buildup, safeguarding sensitive wafers from electrical damage. Lightweight yet durable, they meet the stringent cleanliness and electrostatic protection standards required in wafer shipping, making them a preferred choice for cleanroom environments.

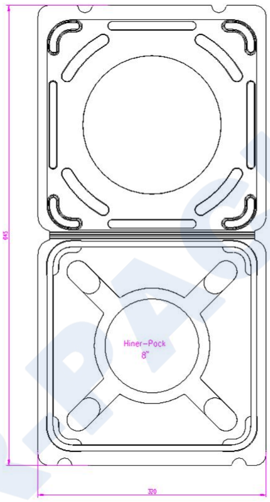
SPECIFICATIONS

- 645 mm L × 320 mm W × 30 mm H (25.39" × 12.6" × 1.18")
- Maximum load capacity is 1 piece

FEATURES & BENEFITS

- Black PET material provides impact resistance and static control
- Secures wafers already mounted on flex, dicing, or film frame
- Designed with secure locking systems to ensure the contents remain protected.
- Vacuum-formed construction is lightweight and stackable

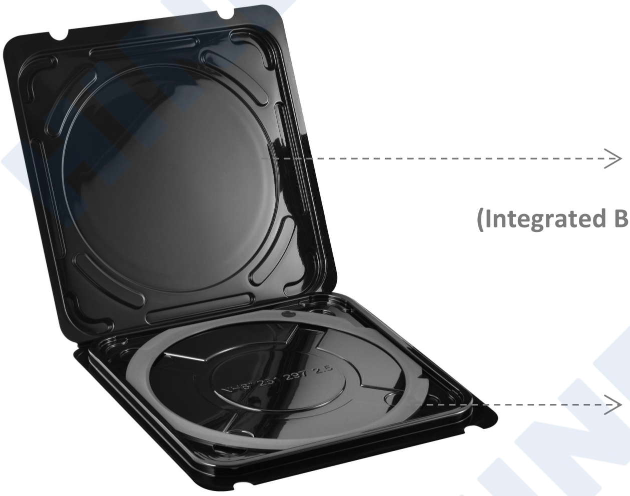
DIMENSION



BASIC INFORMATION

Part Number	Material	Wafer Size
SVFWS-8-BL	PET	200 mm

REFERENCE ILLUSTRATION



The above illustration is for reference only. Please refer to the actual product for accuracy.

TECHNICAL DATA

PROPERTY	RATED VALUES	UNIT
Thickness	0.01-1.00 (+0.01)	mm
Width	510-780 (+1.0)	mm
Density	1.33	g/cm^3
Strength	>60	MPa
Percentage of Breaking Elongation	>200	%
Light Transmittance	>92	%
Glossiness	100	%
Point Defects	1.2 m< 1	--
Bubble	Without	--
Specific Viscosity	0.800+0.020	iv/g
Flame Spot	>243+3	°C
Terminal Acid Group	<30	mol.
Color Value	L>80 B<1.0	-- --
Crystallinity	50~60	%
Diethylene Glycol	<1.6	%
Acetaldehyde	<2.0	%
Moisture	<0.4	%
Ash	<0.02	%
Antistatic Agent	<2.0	%

The information on technical data included in this document is based on our experience to date, and we believe it to be reliable. Data is obtained from specimens molded under controlled conditions from representative samples of the compound described. Properties may be affected by the molding techniques and by the size and shape of the item molded. We cannot guarantee favorable results and no assurances can be implied that all molded articles have the sample properties as those listed.

海纳
新材
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